

Memory Module Specifications

R&D | OEM | ODM SSD & DDRAM

ST32D4N12S816G

SemiTank S8 16GB DDR4 3200 SO-DIMM

DESCRIPTION

This document describes DDR4 260 Pin SO-DIMM Non ECC, P/N: ST32D4N12S816G. This Memory Module based on Capacity 16GB, Frequency 3200 Mhz, Latency CL22, Data Transfer Bandwidth 25.600 MB/s. DDR4 260 Pin SO-DIMM Non ECC uses gold contact fingers and used for: * Laptop.

- * All in One Computer.
- * Industrial Computer.
- * Mini Computer.

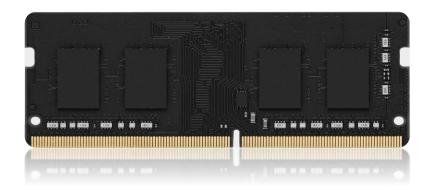
The electrical and mechanical specifications are as follows:

Feature

- Increased Fundamental Frequency, Faster Speeds.
- Unleashed Capacity, Stronger, Multitasking.
- Improved Structural Composition, Greater Efficiency.
- Reduced Working Voltage. Better Energy Efficiency.
- RoHS Compliant and Halogen-Free.

SPECIFICATIONS

Module type	DDR4 260 Pin SO-DIMM Non ECC
Product Dimensions	69.6*30*3.37 mm
Series	S8 Series
Frequency	3200 Mhz
Latency	CL22
Data Transfer Bandwidth	PC4 25600 25.600 MB/s
Capacity	16GB
Capacity Voltage	16GB 1.2V
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Voltage	1.2V
Voltage Operating Temperature	1.2V 0°C to +70°C



*Note:

- We reserve the right to modify product specifications without prior notice.
- Check "Product Compatibility Inquiry" before purchase for further info.